Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	45	spin near coat near apparatus	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 08:03
L2	387	centering near posts	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 08:01
L3	, o	1 and 2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 08:00
L4	4215	spin near coat	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 08:00
L5	O	2 and 4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 08:00
L6	5272 	centering near pins	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 08:01
L7	4	4 and 6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 08:01
L8	0	(spin near coat) and MTI	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 08:03
L9	121	(spin) and MTI	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 08:03

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L10	1694451	semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 08:06
L11	36	9 and 10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 08:04
L12	4	11 and pin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 08:06
L13	10157	center\$4 near guide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 08:06
L14	61916	10 and spin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 08:06
L15	75266	10 and (spin or rpm)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 08:06
L16	51	13 and 14	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 08:08
L17	51	16 and guide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 08:11
L18	713186	17 and pin or post	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 08:11
L19	29 	17 and (pin or post)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 08:17

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L20	40	17 and (rotate or rotating or rotatable (pin or post))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 08:17
L21	17886	((rotate or rotating or rotatable) near (pin or post))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/08/16 08:17
L22	485	21 and 10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 08:18
L23	37	22 and coat	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 08:19
L24	59	22 and spin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 08:19
L25	73	22 and resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 08:44
L26	156	pin chucking	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/08/16 08:45
L27	3599747	rotat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/08/16 08:45
 L28	9	26 near 27	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/08/16 08:47
L29	2	"20040053508"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/08/16 08:52

L30	539	rotat\$4 center\$4 (pin or post)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/08/16 08:53
L31	20931	rotat\$4 center\$4 (pin or post)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2006/08/16 08:52
L32	60023	rotat\$4 center\$4 (pin or post)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2006/08/16 08:52
L33	23	30 and 10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/08/16 08:55
L34	0	30 near edge	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/08/16 08:57
L35	22927	center\$4 near (pin or post)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/08/16 08:58
L36	1294	35 and 10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/08/16 08:59
L37	812	35 and 21	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/08/16 08:59
L38	. 22	37 and 10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	. 2006/08/16 09:23
L39	2	"5,897,379".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/08/16 09:31

L40	1	"6,494,219".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/08/16 10:18
L41	2	"6,056,869".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/08/16 10:59
L43	0	I-shaped dispense manifold	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/08/16 11:46
L44 	119	dispense manifold	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/08/16 11:46
L45	387	rate near I/min	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2006/08/16 12:09
L46	. 0	38 and 45	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ŅEAR	ON	2006/08/16 12:09
L47	13	"5487398".pn. or "5882433".pn. or "11250511".pn. or "6056869".pn. or "2002129385" or "6494219".pn. or "20040053508"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 12:11
L48	0	47 and 45	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 12:11
L49	5	47 and rate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 12:11
S4	22	semix.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 08:56

S6	9	SEMIX adj Incorporated.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 08:57
S7	9	(SEMIX adj Incorporated).as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 08:59
S8	152	EBR and spin and apparatus	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 09:00
S9	3825	spin near coat	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 09:15
S10	1021	EBR	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 09:00
S11	101	backside near rinse	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 09:15
S12	1	S9 and S10 and S11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 09:03
S15	4344066	apparatus	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 09:03
S16 	7	two near nozzel	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 09:12
S18	1	"10/826487"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 11:45

S19	13835	two near nozzle	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 09:13
S20	38	S9 and S19	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 09:14
S22	413	backside same rinse	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 09:15
S24	24	S9 and S15 and (EBR or (edge adj bead adj removal))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 09:23
S26	19	S24 and nozzle	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 09:19
S27	10	S24 and (two near nozzle)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 09:20
S28	9	S24 and (three near nozzle)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 09:23
S29	600	water and (EBR or (edge adj bead adj removal))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 09:23
S30	4	(dispense near water) and (EBR or (edge adj bead adj removal))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 10:37
S31	3868	water and simultaneous and etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 10:03

S33	380	S31 and dispense	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 10:04
S34	218	S33 and nozzle	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 10:04
S35	72	S34 and etchant	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 10:04
S37	6403	protect near substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 10:37
S38	8437	DI adj water	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 10:37
S40	3	S37 same S38	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 10:38
S41	98	S37 and S38	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 10:40
S44	60	(water) near protectant	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 12:47
S45	4	S44 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 10:42
S50	270865	sulfuric	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 10:48

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S51	1323	EBR or (edge adj bead adj removal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 10:48
S52	248054	hydrochloric	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 10:49
S53	128053	S50 and S52	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 10:49
S54	44	S51 and S53	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:02
S55	75	(water) near passivation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 12:53
S56	21	S55 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 12:55
S58	221	(water) near (pre adj treatment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 12:54
S62	537	prepare near surface same water	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 12:54
S63	1622044	semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 12:55
S64	34	S58 and S63	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 12:55

S65	87	S62 and S63	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 12:55
S66	5333662	"1" near fluid near drop near three near seconds to about S55 fluid drop every "second."	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:03
S68	1	about near "1" near fluid near drop near every near second	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:03
S69	86	"1" near drop near second	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:04
S70	41	S69 same (DI or water)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14.14:06
S71	14	(EBR and apparatus).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:12
S72	0	SOB and EBR	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:11
S73	3786495	G	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:11
S74	37	SOG and EBR	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:14
S76	2	(resist and spin and EBR).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:15

S77	80	((resist and spin and EBR) and apparatus)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:16
S78	14	(resist and spin and EBR) and (apparatus).ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:17
S79	50	(edge adj bead adj removal).ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:29
S80	4	S79 and drop	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:20
S81	75 	(edge adj bead adj removal) and drop	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:26
582	400	(edge adj bead adj removal) and (drops per second)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:28
S83	397371	"1" near (drops per second)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:28
S84 	49	S82 and S83	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:27
S85	1	(edge adj bead adj removal) and (drops adj per adj second)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:28
S86	451196	(flow adj rate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:45

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S87 	474	(edge adj bead adj removal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:45
S88	135	S86 and S87	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:29
S89 	0	program near S87	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:45
S90	44	TEI and SOG	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:45
S91	1	S90 and S87	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:48
S92	0	HCL near EBR and MI/min	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:48
S93	0	HCL near EBR	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:48
S94	1	HCL same EBR	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:48
S95	65	HCL and EBR	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 14:48
S96	3	S95 and ml/min	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 15:08

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S97	48	(pulsing near water) and clean	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 15:09
S98	6	S97 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 15:09
S99	68	(pulsed near water) and clean	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 15:10
S10 0	7	S99 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 15:13
S10 1	0	sccm near (DI adj water)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 15:14
S10 2	28	sccm same (DI adj water)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 15:21
S10 3	2	"6793836".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 15:30
S10 4	2	puddle near etch near solution	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 15:31
S10 5	5	puddle near etchant	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 15:31
S10 6	450	water near puddle	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 15:31

S10 7	6	S106 and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 15:33
S10 8	195	wafer near scrub	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 15:34
S10 9	66	S108 and Di	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 15:34
S11 0	0	(".25" adj L/min) near ("2.5" adj L/min)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 11:14
S11 1	0	(".25" adj L/min) same ("2.5" adj L/min)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 11:14
S11 2	0	(".25" adj L/min) and ("2.5" adj L/min)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 11:14
S11 3	5	("250" adj mL/min) and ("2500" adj mL/min)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 11:16
S11 4	2	("250" adj mL/min) same ("2500" adj mL/min)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 11:15
S11 5	0	("250" adj mL/min) near ("2500" adj mL/min)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 11:15
S11 6	1742	("500" adj mL/min)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 11:17

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S11 7	380	S116 and cleaning	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 11:17
S11 8	130	S117 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 11:40
S11 9 	.0	S118 and ("5" adj "sec.")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 11:22
S12 0	0	S118 and ("10" adj "sec.")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 11:23
S12 1	0	S118 and ("9" adj "sec.")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 11:23
S12 2	0	S118 and ("8" adj "sec.")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 11:23
S12 3	0	S118 and ("8" adj sec)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 11:23
S12 4	0	S118 and ("7" adj sec)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 11:23
S12 5	1	S118 and ("5" adj sec)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 11:24
S12 6	0	S118 and ("4" adj sec)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 11:24

S12 7	1	S118 and ("3" adj sec)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 11:24
S12 8	0	S118 and ("6" adj sec)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 11:24
S12 9	27	S118 and (("100" adj rpm) or ("200" adj rpm) or ("300" adj rpm))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 12:06
S13 0 	0	S118 and dispense near time	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 11:40
S13 1	2620	438/689	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 12:06
S13 2	1500	438/680	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 12:06
S13 3	698	438/681	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 12:06
S13 4	1110	438/682	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 12:06
S13 5	1171	438/683	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 12:06
S13 6	290	438/684	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/15 12:06

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S13 7	2	"6056869".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 14:35
S13 8	1	10/704562	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/15 13:23
S13	11281	"500" adj rpm	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/15 13:23
S14 0 	17094	"2000" adj rpm	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/15 13:24
S14 1	17212	rotating near S139 or S140	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/15 13:25
S14 2	3498687	cleaning or removing or etching or etch or remove or clean	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/15 13:40
S14 3	568	S141 with S142	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/15 13:27
S14 4	1838	S141 same S142	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/15 13:27
S14 5	87	S141 near S142	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR ·	ON	2006/08/15 13:27
S14 6	14 !	S145 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/15 13:37

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514 7	1296	S139 and S140	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/15 13:40
S14 8	377	S147 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/15 13:37
S14 9	329	S148 and S142	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/15 13:40
S15 1	516170	(cleaning or removing or etching or etch or remove or clean).ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/15 13:41
S15 2	14	S149 and S151	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/15 16:30
S15 3	1110	ebr	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/15 16:30
S15 4	1435	ebr or (edge adj bead adj removal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/15 17:02
S15 5	340	S154 and rpm	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/15 16:31
S15 6	207	S155 and "1000"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/15 16:31
S15 7	201	S155 and "2000"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/15 16:32

S15 8	232	S155 and "500"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/15 16:32
S15 9	157	S157 and S158	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/15 16:32
S16 0	2	"6,056,869".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/15 17:02
S16 1	711	S154 and metal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/15 17:02
S16 2	3751	(protect or protective) near water	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2006/08/15 17:03
S16 3	2	S161 and S162	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/16 07:59